

Partner Event Program for**TSMC's Fourth Open Innovation Platform® Partner Workshop and First Open Innovation Platform® Ecosystem Forum****TSMC's 4th OIP Partner Workshop & 1st OIP Ecosystem Forum**

	Day1	Day2
Events	OIP Partner Workshop	OIP Ecosystem Forum
Who Should Attend?	TSMC Partners Only	TSMC Partners and Customers
Programs	TSMC Technical Seminar for Partners	- TSMC and Partner Feature Speeches - Partner Presentations to TSMC Customers - Partner Pavillion

Dear TSMC Open Innovation Platform® Partners:

We would like to inform you our upcoming two-day Open Innovation Platform®(OIP) events scheduled for October: The TSMC OIP Partner Workshop on Monday, October 17th and the TSMC OIP Ecosystem Forum on Tuesday, October 18th, both to be held at the San Jose (CA) Convention Center.

The 1st day event, TSMC OIP Partner Workshop changes to a seminar format where partners will receive technical information on 28nm process and design technologies, plus an early look at 20nm design enablement programs. The 2nd day event, TSMC OIP Ecosystem Forum, which TSMC customers will attend, is the first time we offer you a direct OIP marketing venue to reach TSMC customers.

Key benefits of participating at the OIP Ecosystem Forum include:

- » Direct and exclusive access to more than 1,000 of director-level and above executives from TSMC customers to deepen your understanding of emerging design challenges and build key relationships
- » Opportunity to present in the three-track technical afternoon session to TSMC Customers on how TSMC technology is embedded in your products and services
- » Expanded Partner Pavilion space to accommodate more ecosystem partners enabling more intimate dialog with TSMC customers

Please refer to this event program to start planning now and we look forward to your participation in this exciting event!

With best regards,

TSMC Open Innovation Platform® Event Committee

TSMC's 4th OIP Partner Workshop

I. OVERVIEW

- A. Date:** October 17th, 2011 (Monday)
- B. Time:** 08:00 – 13:30
- C. Venue:** San Jose Convention Center, CA
- D. What will you learn:** TSMC's 20nm process and previous technology status and design requirements
- E. Who will attend:** Approximately 250 invited attendees from TSMC OIP partners are expected to join this workshop, including Engineering Vice Presidents and Directors and Business Development Executives and Directors.

II. REGISTRATION

This workshop is an invitation-only and a free-of-charge event. E-mail invitation will go out on August 22th, 2011. On-line registration is expected to be open from August 22th, 2011 to October 14th, 2011. Once your registration is completed, an e-mail confirmation receipt will be sent to the email address provided. Although an on-site registration is available, it will have to go through the same approval process. Therefore, it is strongly recommended that you use the registration website.

TSMC's 1st OIP Ecosystem Forum Event Program

I. OVERVIEW

The TSMC OIP Ecosystem Forum is a first-of-its-kind event organized by TSMC. With this forum, TSMC offers partners an effective marketing venue to reach nearly 1,000 of director-level and above executives from our customers. This forum will feature a day-long, three-track technical conference along with an Ecosystem Pavilion featuring up to 100 partner companies.

The three-track technical afternoon session provides a total of 18 presentation slots, six for each of the three tracks. All partners are eligible to submit papers under a committee review process and all papers will be reviewed on their merit relating to how TSMC technology is embedded in a partner product or service.

- A. Date:** October 18th, 2011 (Tuesday)
- B. Time:** 08:00 – 18:30
- C. Venue:** San Jose Convention Center, CA
- D. What will you learn:** TSMC's 20nm process and previous technology status and design requirements
- E. Who will attend:** The TSMC OIP Ecosystem Forum collaboratively promotes business and technology value of working with TSMC and its Ecosystem partners. TSMC will invite nearly 1,000 of its most valued and loyal customer executives, all of whom will have been hand-picked and approved for significant decision-making ability.

Invitations will be sent primarily to director-level and above executives involved in both design and operations functions and will include embedded systems and software design implementation influencers.

II. CONFERENCE PROGRAM

A. Agenda:

Plenary Session			
8:00	Registration Opens		
9:00 – 9:10	Welcome Remark		Rick Cassidy
9:10 – 9:40	TSMC and its Ecosystem for Innovation		Shang-Yi Chiang
9:40 – 10:00		<i>Coffee Break</i>	
10:00 – 10:30	Partner Feature Talk - ARM		C-level Executive
10:30 – 11:00	Partner Feature Talk - Synopsys		C-level Executive
11:00 – 11:30	Partner Feature Talk - Cadence		C-level Executive
11:30 – 12:00	Partner Feature Talk - Mentor Graphics		C-level Executive
12:00 – 13:00		<i>Lunch</i>	
	IP Track	EDA Track	IP/EDA/Services Track
13:00 – 13:30			
13:30 – 14:00	Call for Papers	Call for Papers	Call for Papers
14:00 – 14:30			
14:30 – 15:00			
15:00 – 15:30		<i>Coffee Break</i>	
15:30 – 16:00			
16:00 – 16:30			
16:30 – 17:00	Call for Papers	Call for Papers	Call for Papers
17:00 – 17:30			
17:30 – 18:30		<i>Networking and Reception</i>	

B. Call for Paper:

The three-track afternoon sessions: Library and IP, EDA, and Design Chain Alliances, will cover a total of 18 presentation topics, six for each of the three tracks, all presented by selected TSMC partners.

Don't miss the opportunity to present the latest in collaborative technical insight to this highly motivated audience. All partners are eligible to submit papers with the speaker's bio for a committee review process. All papers will be reviewed on their merit relating to

» **How TSMC technology is embedded in a partner product or service**

There is no charge to present. Paper abstract submissions are due on June 30th, 2011. For more information about paper submissions, please contact Mr. Tom Quan at tquan@tsmc.com.

C. Important Timelines for Paper Submissions:

- › June 30th Abstract and bio submission deadline
- › July 20th Abstract review committee inform selected presenters
- › August 20th Presenters submit presentation slides
- › October 6th Briefing meeting for presenters
- › October 17th Presentation rehearsal

D. Application Form:

Please use the Appendix I to submit the abstract and the speaker bio.

III. PARTNER PAVILION

The TSMC OIP Ecosystem Pavilion will accommodate up to 80 partners. Applications to join the Ecosystem Pavilion will start on June 15th . Space is available on a first-come, first-serve basis.

›› Booth size:

- (A) 10'x20' per unit at the rate of \$7,000. Register **before July 15th** and enjoy the early bird special for only \$4,000.
- (B) 20'x20' per unit at the rate of \$14,000. Register **before July 15th** and enjoy the early bird special for only \$8,000.
- (C) 20'x40' booths exclusively for the Platinum and Gold Sponsors (Please see "IV. SPONSORSHIP" for more details.)

›› Decoration:

- (A) For 10'x20' booths: black pipe and drape for backdrop and two sides
- (B) For 20'x20' booths: black pipe and drape for backdrop
- (C) For 20'x40' booths: black pipe and drape for backdrop

›› Equipment: One table with two chairs and one power outlet (5 AMP).

GES can be contacted for additional requests and booth set-up services. GES Contact: Ms Christina Hofmann -
Tel: 510.259.5334 / chofmann@ges.com

›› Complementary Pass for Booth Duty:

For each booth unit, partners will receive 4 (booth staff included) complementary registrations and 4 lunch vouchers. Additional partner personnels can attend for a \$300 registration fee per person. Payment details will be available shortly.

›› Booth Setup:

Exhibitor can start the setup from 09:00am to 5:00pm on both Sunday October 16th and Monday October 17th, 2011

1. 20' x 40' and 20' x 20' booths

Move-in time: Sunday October 16 th 9 - 11AM
Set-up time: Sunday October 16 th 1 - 5PM &
Monday October 17th 9AM - 5PM

2. 10' x 20' booths

Move-in time: Monday October 17th 9 -11AM
Set-up time: Monday October 17th 9AM - 5PM

» **Booth Application:**

Please go to our partner registration website:

<https://www.lookingcube.com/tsmc/OIPEcosystemForum/partner.asp>

IV. SPONSORSHIP:

Maximize Your Presence by becoming a sponsor

Become a TSMC OIP EcoSystem Forum sponsor!!! Sponsorship opportunities are available so that all partners, from the largest to the smallest, can maximize their customer exposure. To sign up to become a sponsor, please contact Ms. Micky Huang at micky.huang@hwacomms.com.

A. Platinum Sponsor (limit 2) - \$30,000 - Cadence (Signature), Synposys

- › One 20'x40' booths with 1st priority choice
- › 25 complementary booth tickets
- › Lunch or social hour sponsor
- › Attendee tote bag insert
- › Company logo on all event proceedings
- › One-page advertisement in the event book

B. Gold Sponsor (limit 2) - \$20,000 - ARM, Mentor Graphics

- › One 20'x40' booths with 2nd priority choice
- › 15 complementary tickets
- › Breakfast, morning break or afternoon break sponsor
- › Attendee tote bag insert
- › Company logo on all event proceedings
- › One-page advertisement in the event book

C. Tote Bag Sponsor (limit 1) - \$20,000

- › Company logo printed on one side of the 1,500 attendee tote bags
- › One 20'x20' booths with 1st priority choice
- › 10 complementary tickets

D. Badge & Lanyard Sponsor (limit 1) - \$10,000 - Mentor Graphics

- › Company logo printed on 1,500 attendee badges and lanyards
- › One 10'x20' booths with 1st priority choice
- › Five complementary tickets

E. Wireless Internet Sponsor (limit 1) - \$10,000

- › Company logo table signs on each internet-area table

F. Pen Sponsor (limit 1) - \$4,000

- › Company logo printed on 1,500 pens

G. Bag Insert – (limit 5) - \$1,000 - GUC, SVTC, True Circuits

- › Insert up to 6 pages of collateral added to the attendee bag

H. Social Hour Customer Drawing (limit 8) - \$700

- › Right to add the prize of your choice to the Social Hour attendee drawing

TSMC, The Trusted Technology and Capacity Provider